

SOT581-1

plastic ball grid array package; 352 balls; body 35 x 35 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA352
Package type industry code	BGA352
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
JEITA package outline code	ED-7311-9A
Mounting method type	S (surface mount)
Issue date	23-1-2003

Table 1. Package summary

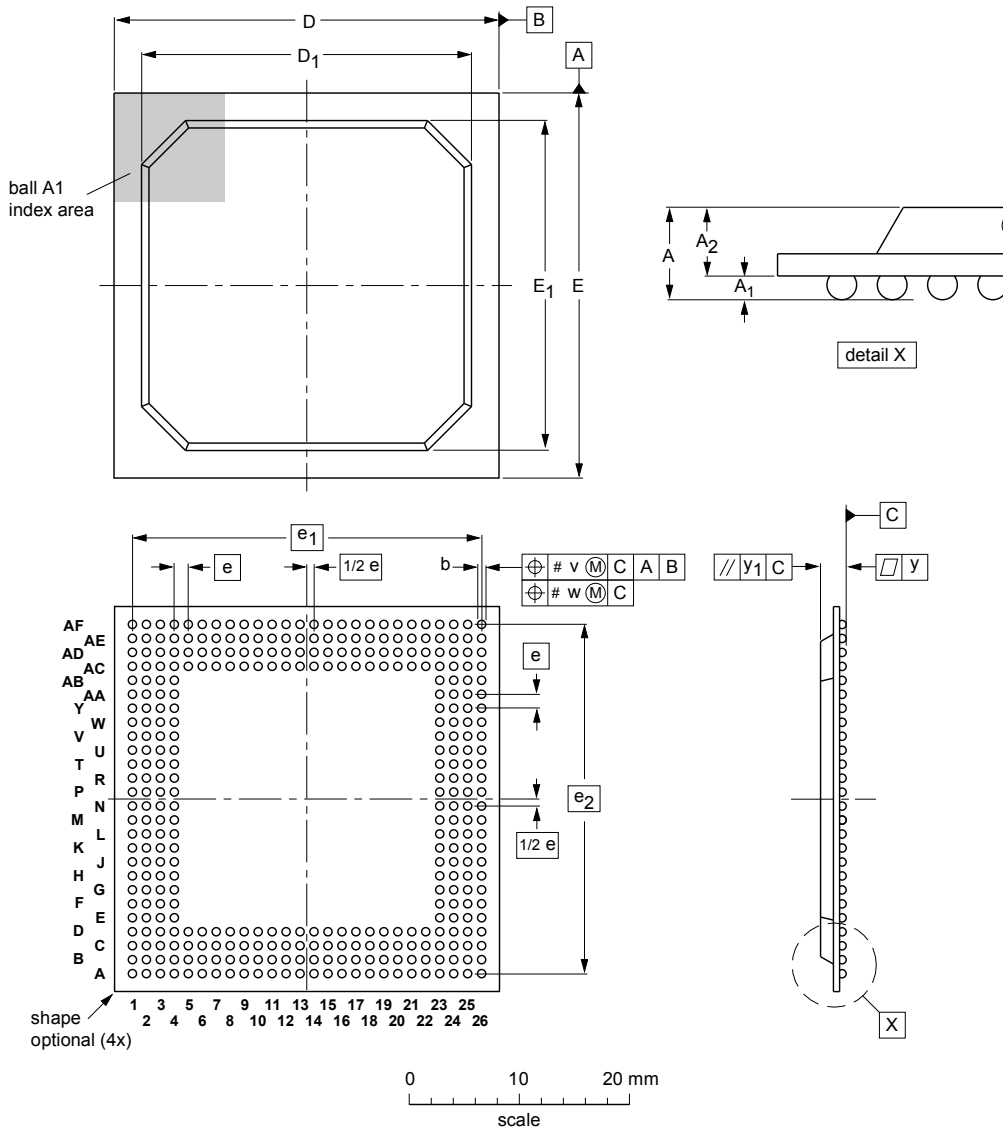
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.8	-	35	35.2	mm
E	package width	34.8	-	35	35.2	mm
A	seated height	[tbd]	-	2.54	2.54	mm
A ₂	package height	1.62	-	1.75	1.84	mm
n ₂	actual quantity of termination	-	-	352	-	



2. Package outline

BGA352: plastic ball grid array package; 352 balls; body 35 x 35 x 1.75 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	v	w	y	y ₁
mm	2.54	0.7 0.5	1.84 1.62	0.9 0.6	35.2 34.8	30.70 29.95	35.2 34.8	30.70 29.95	1.27	31.75	31.75	0.3	0.1	0.15	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT581-1	144E	MS-034	ED-7311-9A			00-03-04- 03-01-23

Fig. 1. Package outline BGA352 (SOT581-1)

3. Soldering

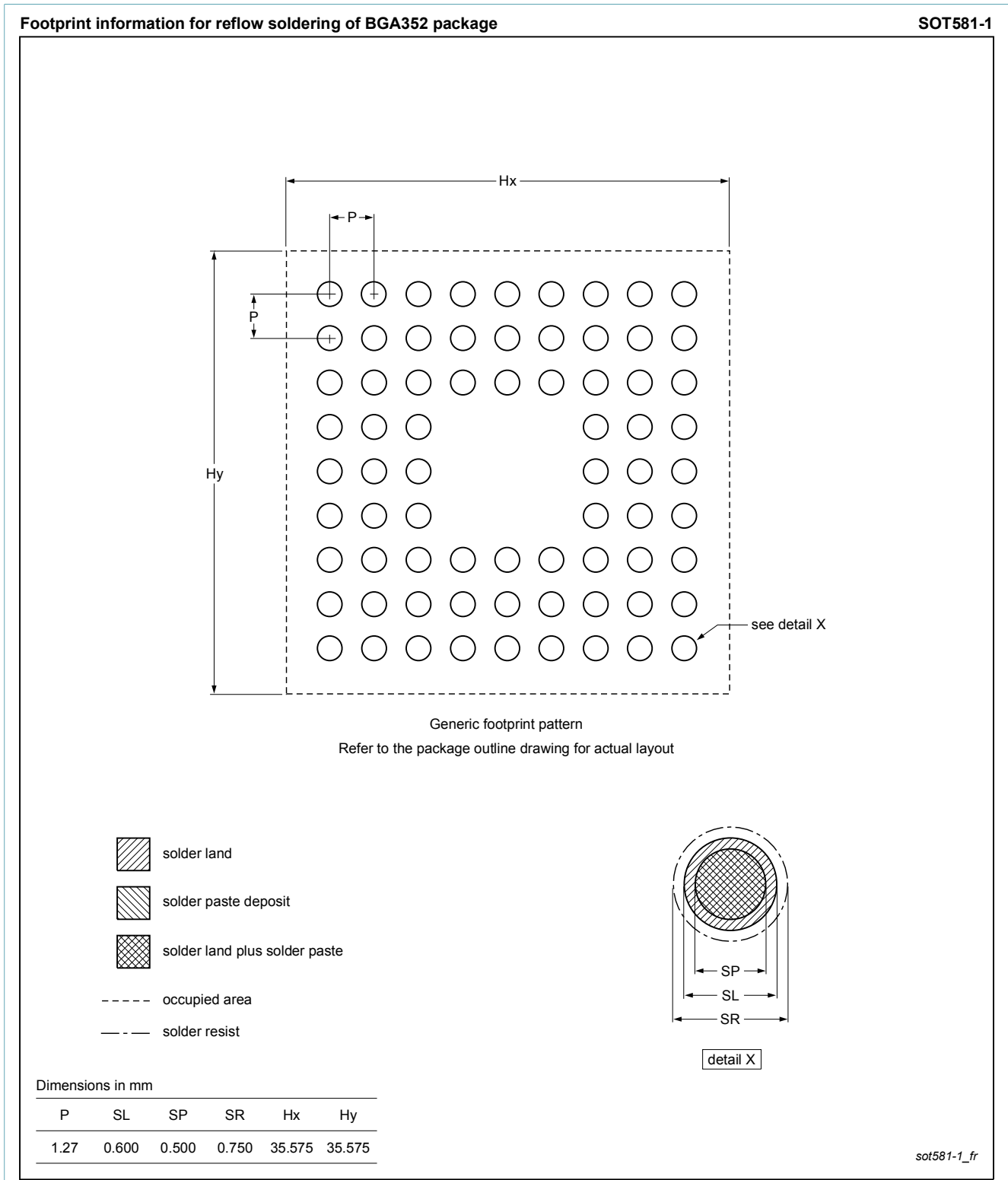


Fig. 2. Reflow soldering footprint for BGA352 (SOT581-1)

4. Legal information

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